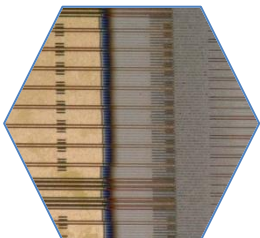
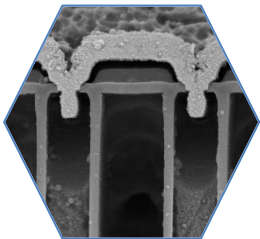


Infineon EasyPACK™ FS100R12W2T7

Discover the newest IGBT technology from Infineon: TRENCHSTOP™ IGBT7 with EC7 diode in EasyPACK™ module.



The market outlook for the power electronics industry is promising. In 2019, the power semiconductor device market segment represented US\$17.5 billion, with a compound annual growth rate (CAGR) for 2019-2025 of 4.3%. IGBT modules, which represent \$3.7B in 2019, are traditionally used in applications such as industrial or renewable energy converters. These applications are today driven by efficiency regulations or increasing clean energy goals, and they account for 46% of the total IGBT module market.

In this dynamic market, Infineon Technologies introduced the new IGBT7 technology for its Easy housing platform in March 2019. Based on the new micro-pattern trench technology, the TRENCHSTOP™ IGBT7 chip has a new cell structure in contrast to the formerly-used square trench cells in IGBT3 and IGBT4.

System Plus Consulting provides a full reverse costing study of the Infineon EasyPACK™ FS100R12W2T7. This power module uses the newest IGBT and Diode technologies from Infineon: TRENCHSTOP™ IGBT7 and EC7 Diode. It drives a nominal current of 100A with a voltage rating of 1200V.

Supported by a full teardown of the module's components and housing, this report reveals Infineon's technological choices in its new IGBT7 chip as well as the design of its diode, and the module packaging structure.

This report provides insights on technology data, manufacturing cost and selling price of all module components. Also included are technology and cost comparisons between Infineon IGBT3, IGBT4, IGBT5, and IGBT7.

COMPLETE TEARDOWN WITH

- Detailed optical and SEM photos
- Precise measurements
- Material EDX analysis
- Manufacturing process flow
- Supply chain evaluation
- Manufacturing cost analysis
- Estimated selling price
- Technology and cost comparisons between Infineon IGBT technologies: IGBT3, IGBT4, IGBT5, and IGBT7

Title: Infineon EasyPACK™ FS100R12W2T7

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Format: PDF & Excel file

Price: EUR 3,990

Reference: SP20572

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AUTHORS



Amine Allouche is part of System Plus Consulting's Power Electronics and Compound Semiconductors team. Amine holds a Master's degree focused on Micro and Nanotechnologies for integrated Systems.



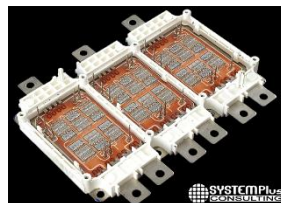
Véronique Le Troadec has joined System Plus Consulting as a laboratory engineer. Coming from Atmel Nantes, she has extensive knowledge in failure analysis of components and in deprocessing of integrated circuits.

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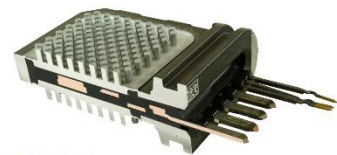
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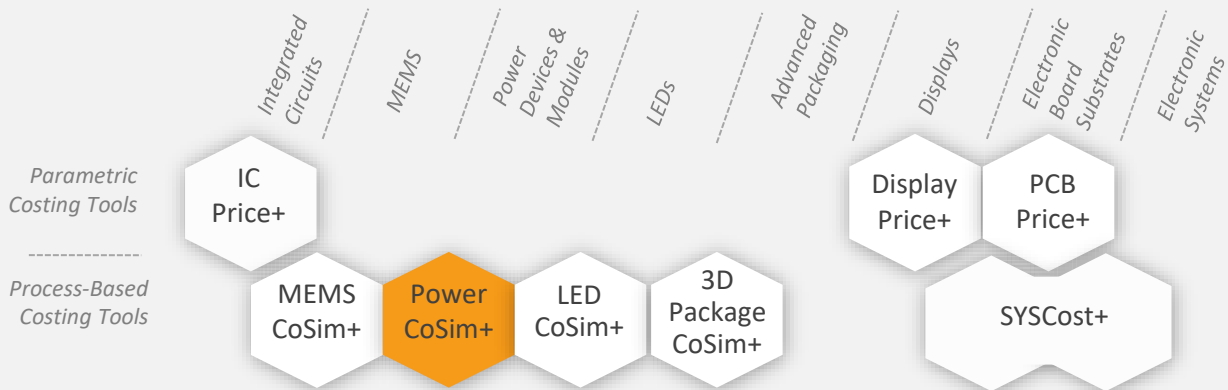
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System Plus Consulting offers powerful costing tools to evaluate the production cost and selling price from single chip to complex structures.

Power CoSim+

Cost simulation tool to evaluate the cost of any Power Electronics process or device: from single chip to complex structures.

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CONTACTS

Headquarters
22, bd Benoni Goullin
Nantes Biotech
44200 Nantes
France
+33 2 40 18 09 16
sales@systemplus.fr

Europe Sales Office
Lizzie LEVENEZ
Frankfurt am Main
Germany
+49 151 23 54 41 82
llevenez@systemplus.fr

America Sales Office
Steven LAFERRIERE
Western USA & Canada
+1 310-600-8267
laferriere@yole.fr

Chris YOUMAN
Eastern USA & Canada
+1 919-607-9839
chris.youman@yole.fr

Asia Sales Office
Takashi ONOZAWA
Japan & Rest of Asia
+81 80 4371 4887
onozawa@yole.fr

Mavis WANG
Greater China
TW +886 979 336 809
CN +8613661566824
wang@yole.fr

Peter OK
Korea
+82 10 4089 0233
peter.ok@yole.fr

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